L Number Hits Search Text DB	Time stamp
2 4609 (257/735-738,777-786).CCLS. USP.	
3 6729 (427/372.2,375,384,385.5,386,407.1).CCLS. USP.	,,
4 1753 (438/612-618).CCLS. USP.	,,
5 3129 (((257/735-738,777-786).CCLS.) USP	
((427/372.2,375,384,385.5,386,407.1).CCLS.)	2003/01/10 13:33
((438/612-618).CCLS.)) and (reflow\$3	
re\$1melt\$3 flow\$3) and (electrode\$1 bump\$1	
pad\$1) and (mount\$3 bond\$3 adhe\$4 tacky	
glu\$3)	
6 2010 ((((257/735-738,777-786).CCLS.) USP	ATT 2003/01/16 15 56
	AT 2003/01/16 15:56
((427/372.2,375,384,385.5,386,407.1).CCLS.) ((438/612-618).CCLS.)) and (reflow\$3	
re\$1melt\$3 flow\$3) and (electrode\$1 bump\$1	
pad\$1) and (mount\$3 bond\$3 adhe\$4 tacky	
glu\$3)) and (resin\$3 epoxy)	
7 210 (((((257/735-738,777-786).CCLS.) USPA	AT 2003/01/16 15:57
((427/372.2,375,384,385.5,386,407.1).CCLS.)	
((438/612-618).CCLS.)) and (reflow\$3	
re\$1melt\$3 flow\$3) and (electrode\$1 bump\$1	
pad\$1) and (mount\$3 bond\$3 adhe\$4 tacky	
glu\$3)) and (resin\$3 epoxy)) and fatigue	
8 171 (((((((257/735-738,777-786).CCLS.) USPA	AT 2003/01/16 15:59
((427/372.2,375,384,385.5,386,407.1).CCLS.)	,
((438/612-618).CCLS.)) and (reflow\$3	
re\$1melt\$3 flow\$3) and (electrode\$1 bump\$1	
pad\$1) and (mount\$3 bond\$3 adhe\$4 tacky	
glu\$3)) and (resin\$3 epoxy)) and fatigue)	
and (solidif\$4 solidification densif\$4	
densification harden\$3 cur\$3)	
9 103 (((((((257/735-738,777-786).CCLS.) USPA	AT 2003/01/16 16:27
((427/372.2,375,384,385.5,386,407.1).CCLS.)	
((438/612-618).CCLS.)) and (reflow\$3	
re\$1melt\$3 flow\$3) and (electrode\$1 bump\$1	
pad\$1) and (mount\$3 bond\$3 adhe\$4 tacky	
glu\$3)) and (resin\$3 epoxy)) and fatigue)	
and (solidif\$4 solidification densif\$4	
densification harden\$3 cur\$3)) and	
(solvent flux\$4)	
10 914 (((((257/735-738,777-786).CCLS.) USPA	AT 2003/01/16 16:26
((((237/7338738,777-7887.66EBS.)) ((427/372.2,375,384,385.5,386,407.1).CCLS.)	2003/01/10 10.20
((427/372.2,373,364,363.3,366,407.1).cclbs.) ((438/612-618).CCLS.)) and (reflow\$3	
re\$1melt\$3 flow\$3) and (electrode\$1 bump\$1	
pad\$1) and (mount\$3 bond\$3 adhe\$4 tacky	
glu\$3)) and (resin\$3 epoxy)) and (wafer\$1	
substrate\$1) same (cut\$4 dic\$3 singulat\$3	
sever\$3)	
11 851 ((((((257/735-738,777-786).CCLS.) USPA	AT 2003/01/16 16:26
	2003/01/10 10:50
((427/372.2,375,384,385.5,386,407.1).CCLS.) ((438/612-618).CCLS.)) and (reflow\$3	
re\$1melt\$3 flow\$3) and (electrode\$1 bump\$1	
pad\$1) and (mount\$3 bond\$3 adhe\$4 tacky	
glu\$3)) and (resin\$3 epoxy)) and (wafer\$1	
substrate\$1) same (cut\$4 dic\$3 singulat\$3	
sever\$3)) not	
(((((((((257/735-738,777-786).CCLS.)	
((427/372.2,375,384,385.5,386,407.1).CCLS.))
((427/372.2,375,384,385.5,386,407.1).CCLS.) ((438/612-618).CCLS.)) and (reflow\$3	
((427/372.2,375,384,385.5,386,407.1).CCLS.) ((438/612-618).CCLS.)) and (reflow\$3 re\$1melt\$3 flow\$3) and (electrode\$1 bump\$1	
((427/372.2,375,384,385.5,386,407.1).CCLS.) ((438/612-618).CCLS.)) and (reflow\$3 re\$1melt\$3 flow\$3) and (electrode\$1 bump\$1 pad\$1) and (mount\$3 bond\$3 adhe\$4 tacky	
((427/372.2,375,384,385.5,386,407.1).CCLS.) ((438/612-618).CCLS.)) and (reflow\$3 re\$1melt\$3 flow\$3) and (electrode\$1 bump\$1 pad\$1) and (mount\$3 bond\$3 adhe\$4 tacky glu\$3)) and (resin\$3 epoxy)) and fatigue)	
((427/372.2,375,384,385.5,386,407.1).CCLS.) ((438/612-618).CCLS.)) and (reflow\$3 re\$1melt\$3 flow\$3) and (electrode\$1 bump\$1 pad\$1) and (mount\$3 bond\$3 adhe\$4 tacky glu\$3)) and (resin\$3 epoxy)) and fatigue) and (solidif\$4 solidification densif\$4	
((427/372.2,375,384,385.5,386,407.1).CCLS.) ((438/612-618).CCLS.)) and (reflow\$3 re\$1melt\$3 flow\$3) and (electrode\$1 bump\$1 pad\$1) and (mount\$3 bond\$3 adhe\$4 tacky glu\$3)) and (resin\$3 epoxy)) and fatigue)	

12	344	(((((((257/735-738,777-786).CCLS.)	USPAT	2003/01/16 16:29
Ì	ļ	((427/372.2,375,384,385.5,386,407.1).CCLS.)		
		((438/612-618).CCLS.)) and (reflow\$3		
		re\$1melt\$3 flow\$3) and (electrode\$1 bump\$1		
		pad\$1) and (mount\$3 bond\$3 adhe\$4 tacky		1
ĺ		glu\$3)) and (resin\$3 epoxy)) and (wafer\$1		
		substrate\$1) same (cut\$4 dic\$3 singulat\$3		
		sever\$3)) not		!
		(((((((257/735-738,777-786).CCLs.)		
1		((427/372.2,375,384,385.5,386,407.1).CCLS.)		
İ		((438/612-618).CCLS.)) and (reflow\$3		
		re\$1melt\$3 flow\$3) and (electrode\$1 bump\$1		
		pad\$1) and (mount\$3 bond\$3 adhe\$4 tacky		İ
		glu\$3)) and (resin\$3 epoxy)) and fatigue)		
		and (solidif\$4 solidification densif\$4		
		densification harden\$3 cur\$3)) and		
		(solvent flux\$4))) and (solvent flux\$4)		
13	252	((((((((257/735-738,777-786).CCLS.)	USPAT	2003/01/16 17:00
		((427/372.2,375,384,385.5,386,407.1).CCLS.)		
		((438/612-618).CCLS.)) and (reflow\$3		
		re\$1melt\$3 flow\$3) and (electrode\$1 bump\$1		
ļ		pad\$1) and (mount\$3 bond\$3 adhe\$4 tacky		
		glu\$3)) and (resin\$3 epoxy)) and (wafer\$1		
		substrate\$1) same (cut\$4 dic\$3 singulat\$3		
		sever\$3)) not		
		((((((((257/735-738,777-786).CCLS.)		
		((427/372.2,375,384,385.5,386,407.1).CCLS.)		
		((438/612-618).CCLS.)) and (reflow\$3		
			1	
		re\$1melt\$3 flow\$3) and (electrode\$1 bump\$1		
}		pad\$1) and (mount\$3 bond\$3 adhe\$4 tacky		
	,	glu\$3)) and (resin\$3 epoxy)) and fatigue)		
1		and (solidif\$4 solidification densif\$4		
1	1	densification harden\$3 cur\$3)) and		
		(solvent flux\$4))) and (solvent flux\$4))		
	'	and (fill\$3 under\$1fill\$3)		
14	20	' ' ' ' ' ' ' ' ' ' ' ' ' ' ' ' ' ' '	USPAT	2003/01/16 17:07
	,	((427/372.2,375,384,385.5,386,407.1).CCLS.)		
ļ		((438/612-618).CCLS.)) and (reflow\$3		
		re\$1melt\$3 flow\$3) and (electrode\$1 bump\$1		
		pad\$1) and (mount\$3 bond\$3 adhe\$4 tacky		
•		glu\$3)) and (resin\$3 epoxy)) and (wafer\$1		
		substrate\$1) same (cut\$4 dic\$3 singulat\$3		
		sever\$3)) not		
		((((((((257/735-738,777-786).CCLS.)		
		((427/372.2,375,384,385.5,386,407.1).CCLS.)		
		((438/612-618).CCLS.)) and (reflow\$3		
		re\$1melt\$3 flow\$3) and (electrode\$1 bump\$1		
		pad\$1) and (mount\$3 bond\$3 adhe\$4 tacky		
		glu\$3)) and (resin\$3 epoxy)) and fatigue)		
		and (solidif\$4 solidification densif\$4		
		densification harden\$3 cur\$3)) and		
		(solvent flux\$4))) and (solvent flux\$4))		
L		and (fill\$3 under\$1fill\$3)) and wafer\$1		L
		near3 level		

03/01/16 17:07